Product data sheet

1. General description

Planar passivated high commutation three quadrant triac in a IITO220 internally insulated plastic package intended for use in circuits where high static and dynamic dV/dt and high dI/dt can occur. This "series C" triac will commutate the full RMS current at the maximum rated junction temperature without the aid of a snubber. This device has high T_j operating capability and an internally isolated mounting base.

2. Features and benefits

- · 3Q technology for improved noise immunity
- High commutation capability with maximum false trigger immunity
- · High immunity to false turn-on by dV/dt
- High surge capability
- High T_{i(max)}
- Isolated mounting base with 2500 V (RMS) isolation
- · Less sensitive gate for high noise immunity
- · Planar passivated for voltage ruggedness and reliability
- · Triggering in three quadrants only
- UL1557 certified (Document number E346397)

3. Applications

- · Electronic thermostats (heating and cooling)
- · High power motor controls
- · Rectifier-fed DC inductive loads e.g. DC motors and solenoids

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Absolute	maximum rating					
V_{DRM}	repetitive peak off-state voltage		-	-	600	V
I _{T(RMS)}	RMS on-state current	full sine wave; $T_{mb} \le 108 ^{\circ}\text{C}$; Fig. 1; Fig. 2; Fig. 3	-	-	16	А
I _{TSM}	non-repetitive peak on- state current	full sine wave; $T_{j(init)}$ = 25 °C; t_p = 20 ms; Fig. 4; Fig. 5	-	-	160	А
		full sine wave; $T_{j(init)}$ = 25 °C; t_p = 16.7 ms	-	-	176	Α
T _j	junction temperature		-	-	150	°C
Static ch	aracteristics					
I _{GT}	gate trigger current	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2+ \text{ G+;}$ $T_j = 25 \text{ °C; } Fig. 7$	2	-	35	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G-;$ $T_j = 25 \text{ °C; } Fig. 7$	2	-	35	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; T2- G-;}$ $T_j = 25 \text{ °C; Fig. 7}$	2	-	35	mA

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u>	-	-	35	mA
V _T	on-state voltage	I _T = 20 A; T _j = 25 °C; <u>Fig. 10</u>	-	1.2	1.5	V
Dynamic	characteristics		,	,		
dV _D /dt rate of rise of off-state voltage	rate of rise of off-state voltage	V_{DM} = 402 V; T_j = 125 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	1000	-	-	V/µs
		V_{DM} = 402 V; T_j = 150 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	500	-	-	V/µs
dl _{com} /dt rate of change of commutating current		$V_D = 400 \text{ V}; T_j = 125 ^{\circ}\text{C}; I_{T(RMS)} = 16 \text{ A};$ $dV_{com}/dt = 20 \text{ V}/\mu\text{s}; \text{ (snubberless condition)}; \text{ gate open circuit}$	10	-	-	A/ms
		V_D = 400 V; T_j = 150 °C; $I_{T(RMS)}$ = 16 A; dV_{com}/dt = 20 V/ μ s; (snubberless condition); gate open circuit	5	-	-	A/ms

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1	mb	N.
2	T2	main terminal 2		T2 — T1
3	G	gate		sym051
mb	n.c.	mounting base; isolated		

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BTA416Y-600C	IITO220	BTA416Y-600C,127	Tube	50	SOT78D (A)	10-July-2007
					IITO220P (P)	31-Mar-2023

7. Marking

Table 4. Marking codes

Type number	Marking codes		
	Assembly factory: A	Assembly factory: P	
BTA416Y-600C	BTA416Y 600C PJAxxxx xx	BTA416Y 600C PJPxxxx xx	

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	600	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; T _{mb} ≤ 108 °C; Fig 1; Fig 2; Fig 3	-	16	Α
I _{TSM}	non-repetitive peak on- state current	full sine wave; $T_{j(init)}$ = 25 °C; t_p = 20 ms; Fig 4; Fig 5	-	160	Α
		full sine wave; $T_{j(init)} = 25 ^{\circ}\text{C}$; $t_p = 16.7 \text{ms}$	-	176	Α
l ² t	I ² t for fusing	t _P = 10 ms; SIN	-	128	A ² s
dl _⊤ /dt	rate of rise of on-state current	I _G = 0.2 A	-	100	A/µs
I _{GM}	peak gate current		-	2	Α
P_{GM}	peak gate power		-	5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	0.5	W
T _{stg}	storage temperature		-40	150	°C
T _j	junction temperature		-	150	°C

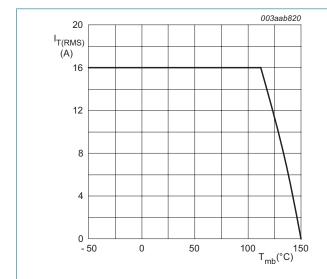
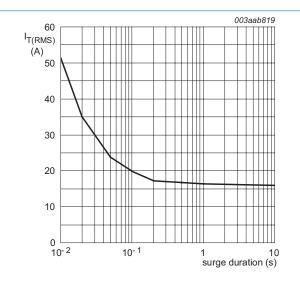
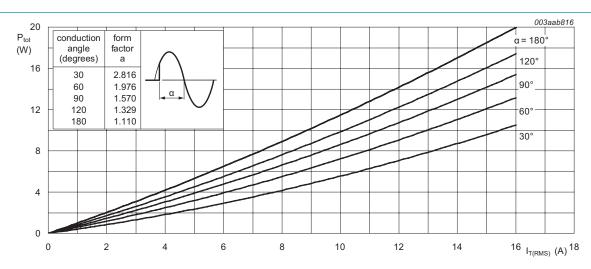


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values



 $f = 50 \text{ Hz}; T_h = 108 \text{ }^{\circ}\text{C}$

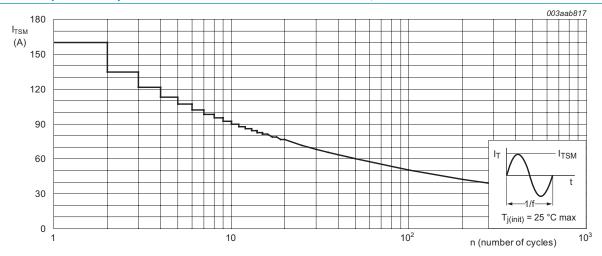
Fig. 2. RMS on-state current as a function of surge duration; maximum values



 α = conduction angle

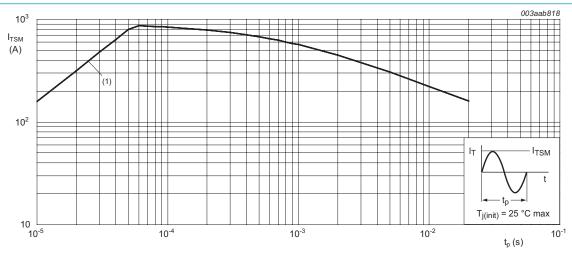
a = form factor = $I_{T(RMS)}$ / $I_{T(AV)}$

Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values



f = 50 Hz

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



 $t_p \le 20 \text{ ms}$ (1) $dI_T/dt \text{ limit}$

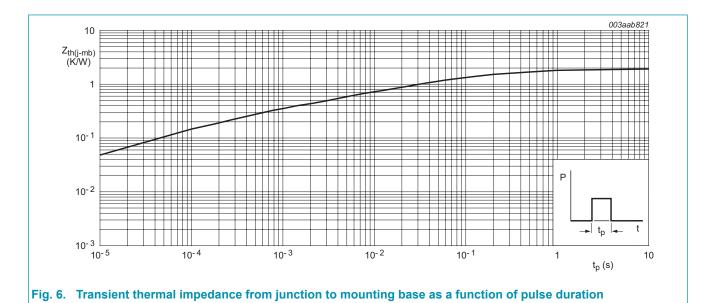
Fig. 5. Non-repetitive peak on-state current as a function of pulse duration; maximum values

4 / 13

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base	full cycle; Fig. 6	-	-	1.9	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient	in free air	-	60	-	K/W



10. Isolation characteristics

Table 7. Isolation characteristics

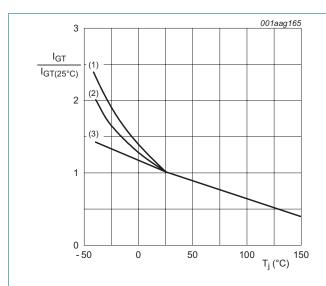
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{isol(RMS)}	RMS isolation voltage	from all terminals to external heatsink; sinusoidal waveform; clean and dust free; 50 Hz \leq f \leq 60 Hz; RH \leq 65 %; $T_h = 25$ °C	-	-	2500	V
C _{isol}	isolation capacitance	from main terminal 2 to external heatsink; f = 1 MHz; T _h = 25 °C	-	10	-	pF

11. Characteristics

Table 8. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static ch	aracteristics					
I _{GT}	gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2+ G+; T_j = 25 °C; Fig. 7$	2	-	35	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2+ G-; $ $T_j = 25 \text{ °C}; Fig. 7$	2	-	35	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; \text{ T2- G-};$ $T_j = 25 \text{ °C}; \text{Fig. 7}$	2	-	35	mA
I _L	latching current	V _D = 12 V; I _G = 0.1 A; T2+ G+; T _j = 25 °C; <u>Fig. 8</u>	-	-	50	mA
		$V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{ T2+ G-};$ $T_j = 25 \text{ °C}; \text{Fig. 8}$	-	-	60	mA
		V _D = 12 V; I _G = 0.1 A; T2- G-; T _j = 25 °C; <u>Fig. 8</u>	-	-	50	mA
I _H	holding current $V_D = 12 \text{ V}; T_j = 25 \text{ °C}; Fig. 9$		-	-	35	mA
V _T	on-state voltage	I _T = 20 A; T _j = 25 °C; <u>Fig. 10</u>	-	1.2	1.5	V
V _{GT} g	gate trigger voltage	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C};$ Fig. 11	-	0.7	1	V
		$V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_j = 150 ^{\circ}\text{C}$	0.25	0.4	-	V
I _D	off-state current	V _D = 600 V; T _j = 125 °C	-	0.1	0.5	mA
		V _D = 600 V; T _j = 150 °C	-	0.4	2	mA
Dynamic	characteristics					
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 402 V; T_j = 125 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	1000	-	-	V/µs
		V_{DM} = 402 V; T_j = 150 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	500	-	-	V/µs
dl _{com} /dt	rate of change of commutating current	$V_D = 400 \text{ V}; T_j = 125 \text{ °C}; I_{T(RMS)} = 16 \text{ A};$ $dV_{com}/dt = 20 \text{ V/}\mu\text{s}; (snubberless condition); gate open circuit$	10	-	-	A/ms
		$V_D = 400 \text{ V}; T_j = 150 \text{ °C}; I_{T(RMS)} = 16 \text{ A};$ $dV_{com}/dt = 20 \text{ V/}\mu\text{s}; \text{ (snubberless condition)}; \text{ gate open circuit}$	5	-	-	A/ms

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- (1) T2- G-
- (2) T2+ G-
- (3) T2+ G+

Fig. 7. Normalized gate trigger current as a function of junction temperature

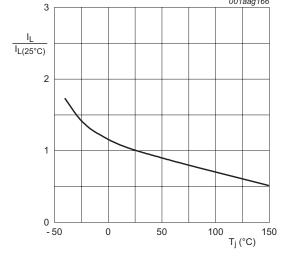


Fig. 8. Normalized latching current as a function of junction temperature

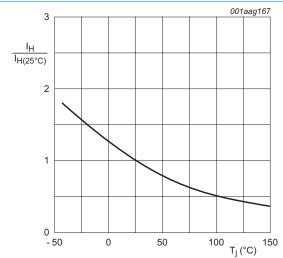
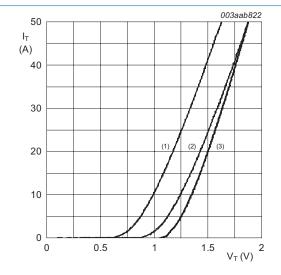


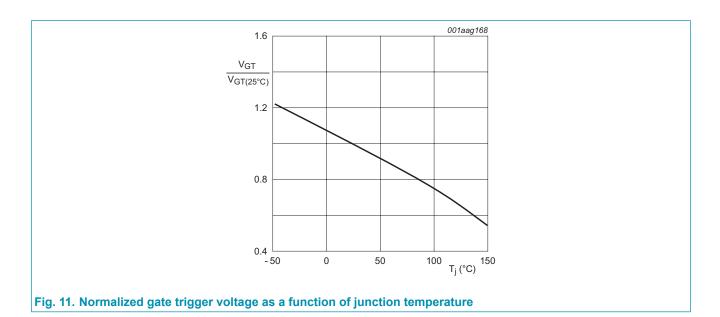
Fig. 9. Normalized holding current as a function of junction temperature



 V_o = 1.086 V; R_s = 0.017 Ω

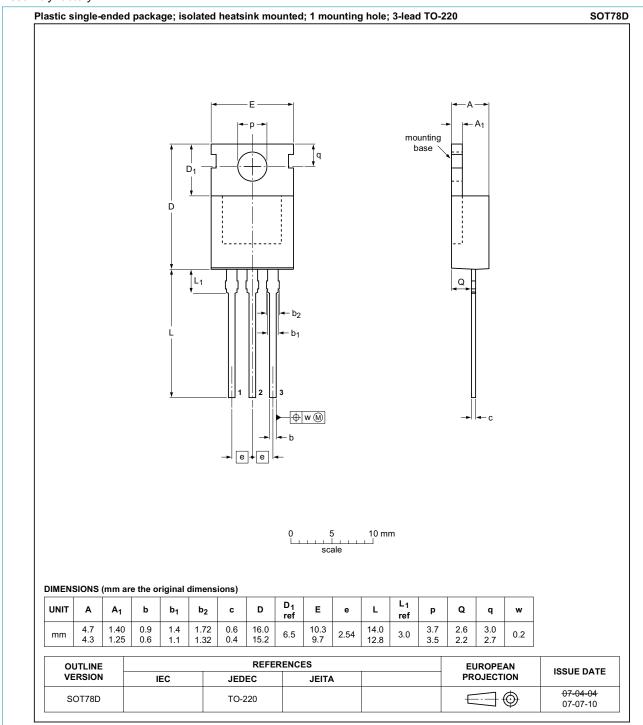
(1) $T_j = 150 \,^{\circ}\text{C}$; typical values (2) $T_j = 150 \,^{\circ}\text{C}$; maximum values (3) $T_j = 25 \,^{\circ}\text{C}$; maximum values

Fig. 10. On-state current as a function of on-state voltage

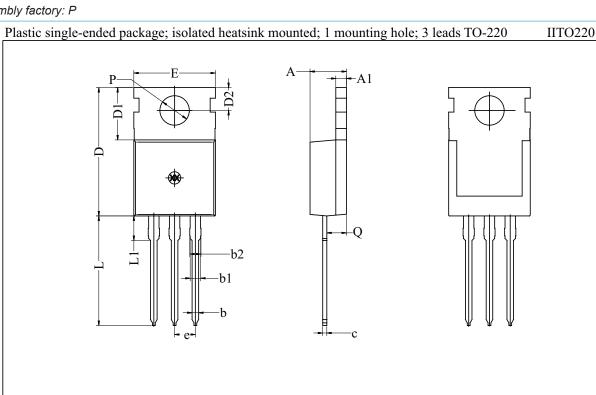


12. Package outline

Assembly factory: A



Assembly factory: P



Dim	All Dimensions in Millimeters					
Diiii	Min	Тур	Max			
A	4.30	4.45	4.70			
A1	1.25	1.30	1.40			
b	0.60	0.80	0.90			
b1	1.10	1.27	1.40			
b2	1.32	1.37	1.72			
с	0.40	0.50	0.60			
D	15.20	15.70	16.00			
D1	6.20	6.40	6.60			
D2	2.70	2.80	3.00			
Е	9.70	10.00	10.30			
e		2.54 BSC				
L	12.80	13.40	14.00			
L1	2.80	3.00	3.20			
P	3.50	3.60	3.70			
Q	2.20	2.40	2.60			

13. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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BTA416Y-600C

3Q Hi-Com Triac

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14. Contents

1. General description	1
2. Features and benefits	1
3. Applications	1
4. Quick reference data	1
5. Pinning information	2
6. Ordering information	2
7. Marking	
8. Limiting values	3
9. Thermal characteristics	5
10. Isolation Characteristics	5
11. Characteristics	6
12. Package outline	9
13. Legal information	
14. Contents	

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